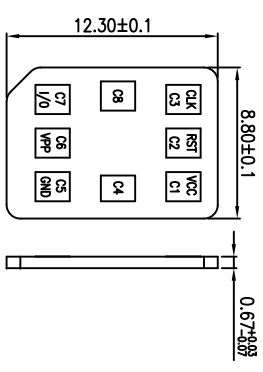
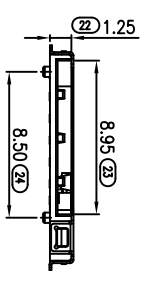
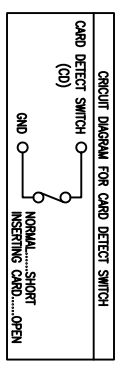


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

PAD
 KEEP OUT AREA



- NOTES:
- 1) MATERIAL:
HOUSING: HIGH-TEMP. PLASTIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
 - 2) PLATING:
TERMINAL:
CONTACT AREA: Au GOLD FLASH;
SOLDER AREA: Au GOLD FLASH;
UNDER PLATE: NICKEL;
SHELL: NICKEL PLATED OVER ALL;
SOLDER AREA: GOLD FLASH.
 3. SPECIALTY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 50mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0/-5°C, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature: -40°C~+85°C;
Humidity: 80% RH MAX



SIM pin Assignment	
PIN#	Nome
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NO	DATE	DESCRIPTION OF REVISION	DESIGNED	CHECKED	APPROVED	MATERIAL		SPECIFICATION		FINISH	QUANTITY	SCALE
						작 성	검 토	승 인	규 격			
변경일차	변경내용	작 성	검 토	승 인	DESIGNED	CHECKED	APPROVAL	DRAWING NUMBER				UNIT 단위
					김도현	박재규	최국호	부품명	HY-NANO-113			mm
								MODEL NAME	HY-NANO-113			
DESIGNED								3RD ANGLE PROJ	HANYONES TECH CO.,LTD			FILE NO.
작성												

